

**LISTING OF CLAIMS:**

This Listing of Claims will replace all prior versions, and listings, of claims in the application.

1. (Currently amended) A pressure-sensitive adhesive sheet comprising a base material and a pressure-sensitive adhesive layer, having formed therein a plurality of through holes passing through from one surface to the other surface thereof, and being exposed at maximum temperature  $T_{\max}$  (wherein  $20\text{ }^{\circ}\text{C} \leq T_{\max} \leq 130\text{ }^{\circ}\text{C}$ ) after having been stuck onto an adherend, ~~the pressure-sensitive adhesive sheet characterized in that~~wherein:

said through holes have a diameter in said base material and said pressure-sensitive adhesive layer in a range of ~~0.1 to 300~~ 0.5 to 150  $\mu\text{m}$ , and a hole density in a range of 30 to 50,000 per  $100\text{ cm}^2$ ;

and said pressure-sensitive adhesive layer has a storage modulus at  $T_{\max}$  of not less than  $4.5 \times 10^3\text{ Pa}$ , and a loss tangent at  $T_{\max}$  of not more than 0.78.

2. (Currently amended) A pressure-sensitive adhesive sheet comprising a base material and a pressure-sensitive adhesive layer, and having formed therein a plurality of through holes passing through from one surface to the other surface thereof, ~~the pressure-sensitive adhesive sheet characterized in that~~wherein:

said through holes have a diameter in said base material and said pressure-sensitive adhesive layer in a range of ~~0.1 to 300~~ 0.5 to 150  $\mu\text{m}$ , and a hole density in a range of 30 to 50,000 per 100  $\text{cm}^2$ ;

and said pressure-sensitive adhesive layer has a storage modulus at 120 °C of not less than  $4.5 \times 10^3$  Pa, and a loss tangent at 120 °C of not more than 0.78.

3. (Currently amended) The pressure-sensitive adhesive sheet according to claim 1 or 2, ~~characterized in that~~ wherein said through holes comprise laser processed through holes ~~are formed by laser processing.~~